ABSTRACT

PBGA SUBSTRATE FOR ANCHORING HEAT SINK

In accordance with the objectives of the invention a new method is provided to position and secure a heat sink over the surface of a semiconductor device mounting support, the latter typically being referred to as a semiconductor substrate. A plurality of recesses is created in the surface of the substrate over which the heat sink is to be mounted. The heat sink is (conventionally and not part of the invention) provided with dimples that form the interface between the heat sink and the underlying substrate. The dimples of the heat sink are aligned with and inserted into the recesses that have been created by the invention in the underlying substrate for this purpose, firmly securing the heat sink in position with respect to the substrate.

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)